PRODUCTION OF ELECTRONIC PARTS
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PURPOSE: To bury an electronic parts into a dielectric and shear a lead frame at the same time, by placing a preformed dielectric in a cavity of a die and pressing a punch against it after placing on it the lead frame which is provided with the electronic parts by die bonding.
CONSTITUTION: A prescribed amount of preformed resin 13, such as polyphloroethylene, etc., is placed in a cavity 12 of a die 11. A lead frame 4, which is provided by die bonding with an electronic part 5 such as silicon semiconductor element, etc., is pressed against the top of the cavity 12 of the die 11 by means of a holding board 15. In the condition that these are being heated at an appropriate temperature, a punch 9 is pushed into shear the lead frame. The resin of an appropriate viscosity is extruded around the electronic part 5 on the lead framd through the lead frame's penetrating hole 8 and formed into a dielectric layer 7. It is possible, by using this method, to increase mechanical strength and heat dissipation of the electronic part without changing number of work processes and also, at the same time, to shear the lead frame into a required shape in the same work process as the formation of the dielectic layer.

NO-DESCRIPTORS .